



Title of Change:	Wire conversion from 0.8mils Au wire to 0.8mils bare Cu wire for SOT23 SL05 devices.								
Proposed first ship date:	11 October 2017								
Contact information:	Contact your local ON Semiconductor Sales Office or <Coleen.Long@onsemi.com>								
Samples:	Contact your local ON Semiconductor Sales Office								
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <Rui.Zhang@onsemi.com>.								
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.								
Change Part Identification:	After expired of the FPCN, devices will be assembled with 0.8mils bare Cu Wire at ON Semiconductor's existing Leshan facility. Products assembled with 0.8mils bare Cu Wire from the ON Semiconductor facility will have a Finish Goods Date Code of WW38, 2017 or greater.								
Change category:	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input checked="" type="checkbox"/> Other <u>Wire Bonding change</u>								
Change Sub-Category(s):	<input type="checkbox"/> Manufacturing Site Change/Addition <input checked="" type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____								
Sites Affected:	<input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable <input checked="" type="checkbox"/> ON Semiconductor site(s) : ON Leshan, China _____ <input type="checkbox"/> External Foundry/Subcon site(s)								
Description and Purpose:									
ON Semiconductor is notifying customer of its use 0.8mils bare Cu wire for SOT23 SL05 series device at ON Semiconductor's Leshan, China facility. Upon the expiration of the PCN, devices will be built with 0.8mils bare Cu wire at the same site. Datasheet specifications and product electrical performance remain unchanged. Reliability Qualification and full electrical characterization over temperature have been performed.									
<table border="1"> <thead> <tr> <th>Material to be changed</th> <th>Before Change Description</th> <th>After Change Description</th> </tr> </thead> <tbody> <tr> <td>Bonding Wire</td> <td>0.8mil Au Wire</td> <td>0.8mil Cu Wire</td> </tr> </tbody> </table>				Material to be changed	Before Change Description	After Change Description	Bonding Wire	0.8mil Au Wire	0.8mil Cu Wire
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Bonding Wire	0.8mil Au Wire	0.8mil Cu Wire							

**Reliability Data Summary:**

Qualification Vehicle: SZSL24T1G

PACKAGE: SOT23

Test	Specification	Condition	Interval	Results
PC	JESD22-A113	MSL 1 @ 260 °C	Before TC, AC, H3TRB, IOL	0/924
AC	JESD22-A102	121°C, 100% RH, ~15psig, unbiased	192 hrs	0/231
TC	JESD22-A104	Ta = - 65°C to +150°C	2000 cyc	0/231
H3TRB	JESD22-A101	85°C, 85% RH, V=80% rated V or 100V max.	2016 hrs	0/231
IOL	MIL-STD-750 (M1037)	Ta=+25°C, delta Tj=100°C On/off = 2 min	30000 cyc	0/231
HTRB	MIL-STD750-1	Tj= max, V=100% rated V, 1008 Hrs	1008	0/231
HTSL	JESD22- A103	Temp.=165°C, no bias, 2016 hours	2016hrs	0/231
RSH	JESD22- B106	Ta = 265C, 10 sec	-	0/30

Electrical Characteristic Summary:

Three temperature characterization and ESD performance meet datasheet specification. Detail of Electrical characterization result is available upon request.

List of Affected Standard Parts:

Part Number	Qualification Vehicle
SL05T1G	SZSL24T1G
SL12T1G	
SL15T1G	
SL24T1G	